

Filename: BOM-ISE4029(001).xls

Variant: 001

Generated: 3/25/2015 9:13:43 AM

### TIDA-00379: 110VAC to 5VDC/30mA Non-Isolated Power Supply

Designator	Description	Manufacturer	PartNumber	Quantity
!PCB	Printed Circuit Board	Any	TIDA-00379	1
C1	CAP, CERM, 0.1 $\mu$ F, 50 V, +/- 10%, X7R, 1206	AVX	12065C104KAT2A	1
C2	CAP, CERM, 0.1 $\mu$ F, 16 V, +/- 10%, X7R, 0603	Kemet	C0603C104K4RACTU	1
C3, C4	CAP, CERM, 1 $\mu$ F, 250 V, +/- 10%, X7R, 2220	MuRata	GRM55DR72E105KW01L	2
C5	CAP, CERM, 22 $\mu$ F, 25 V, +/- 20%, X5R, 0805	MuRata	GRM21BR61E226ME44	1
C8	CAP, CERM, 1 $\mu$ F, 25 V, +/- 10%, X7R, 0805	TDK	C2012X7R1E105K	1
C9	CAP, CERM, 2.2 $\mu$ F, 10 V, +/- 10%, X7R, 1206	MuRata	GRM31MR71A225KA01L	1
D1, D2, D3, D4	Diode, Ultrafast, 400 V, 1 A, 1408 Diode	Bourns	CD1408-FU1400	4
H9, H10, H11, H12	Bumpon, Hemisphere, 0.44 X 0.20, Clear	3M	SJ-5303 (CLEAR)	4
L1	Inductor, Drum Core, Ferrite, 470 $\mu$ H, 0.11 A, 14.3 ohm, SMD	Bourns	SDR0302-471KL	1
L2	Inductor, Unshielded Drum Core, Ferrite, 680 $\mu$ H, 0.3 A, 2.2 ohm, SMD	TDK	VLP8040T-681M	1
R1	RES, 61.9 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-0761K9L	1
R2	RES, 10.2 k, 1%, 0.1 W, 0603	Yageo America	RC0603FR-0710K2L	1
R6	RES, 24.9 k, 1%, 0.125 W, 0805	Vishay-Dale	CRCW080524K9FKEA	1
RF1	RES, 10, 5%, 3 W, Fusible, TH	Vishay-Bccomponents	AC03000001009JACCS	1
TP1, TP2	Test Point, Miniature, Red, TH	Keystone	5000	2
TP3, TP4	Test Point, Miniature, Black, TH	Keystone	5001	2
U1	700-V Lowest Quiescent Current Off-Line Switcher, D0007A	Texas Instruments	UCC28880DR	1
U2	150-mA Low-noise Low-dropout Regulator With Shutdown, DBV0005A	Texas Instruments	LP2985-50DBVR	1

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